



BSI Standards Publication

Semiconductor devices — Mechanical and climatic test methods

Part 22-1: Bond strength — wire bond pull test methods

National foreword

This British Standard is the UK implementation of EN IEC 60749-22-1:2026. It is identical to IEC 60749-22-1:2025. Together with BS EN IEC 60749-22-2:2026, it partially supersedes BS EN 60749-22:2003, which will be withdrawn on 31 January 2029.

The UK participation in its preparation was entrusted to Technical Committee EPL/46, Cables, wires and waveguides, radio frequency connectors and accessories for communication and signalling.

A list of organizations represented on this committee can be obtained on request to its committee manager.

Contractual and legal considerations

This publication has been prepared in good faith, however no representation, warranty, assurance or undertaking (express or implied) is or will be made, and no responsibility or liability is or will be accepted by BSI in relation to the adequacy, accuracy, completeness or reasonableness of this publication. All and any such responsibility and liability is expressly disclaimed to the full extent permitted by the law.

This publication is provided as is, and is to be used at the recipient's own risk.

The recipient is advised to consider seeking professional guidance with respect to its use of this publication.

This publication is not intended to constitute a contract. Users are responsible for its correct application.

© The British Standards Institution 2026
Published by BSI Standards Limited 2026

ISBN 978 0 539 34038 9

ICS 29.100.10; 31.080.01

Compliance with a British Standard cannot confer immunity from legal obligations.

This British Standard was published under the authority of the Standards Policy and Strategy Committee on 31 January 2026.

Amendments/corrigenda issued since publication

Date	Text affected
------	---------------